

MIC-6110

6U OpenVPX MXM carrier

Preliminary



Features

- OpenVPX MOD6-PER-4F-12.3.1-3 profile compliant
- MXM 3.1 type A/type B compliant
- Up to 4 independent outputs
- PCIe fabric interface
- Ruggedized convection cooled thermal solution



Introduction

MIC-6110 is a 6U OpenVPX MXM carrier. MIC-6110 complies with the MOD6-PER-4F-12.3.1-3 profile, and the newest MXM specification rev. 3.1. Connecting to the Dataplane by the PCIe fabric x 16, MIC-6110 is capable to leverage the advantages of the MXM module with the optimized performance.

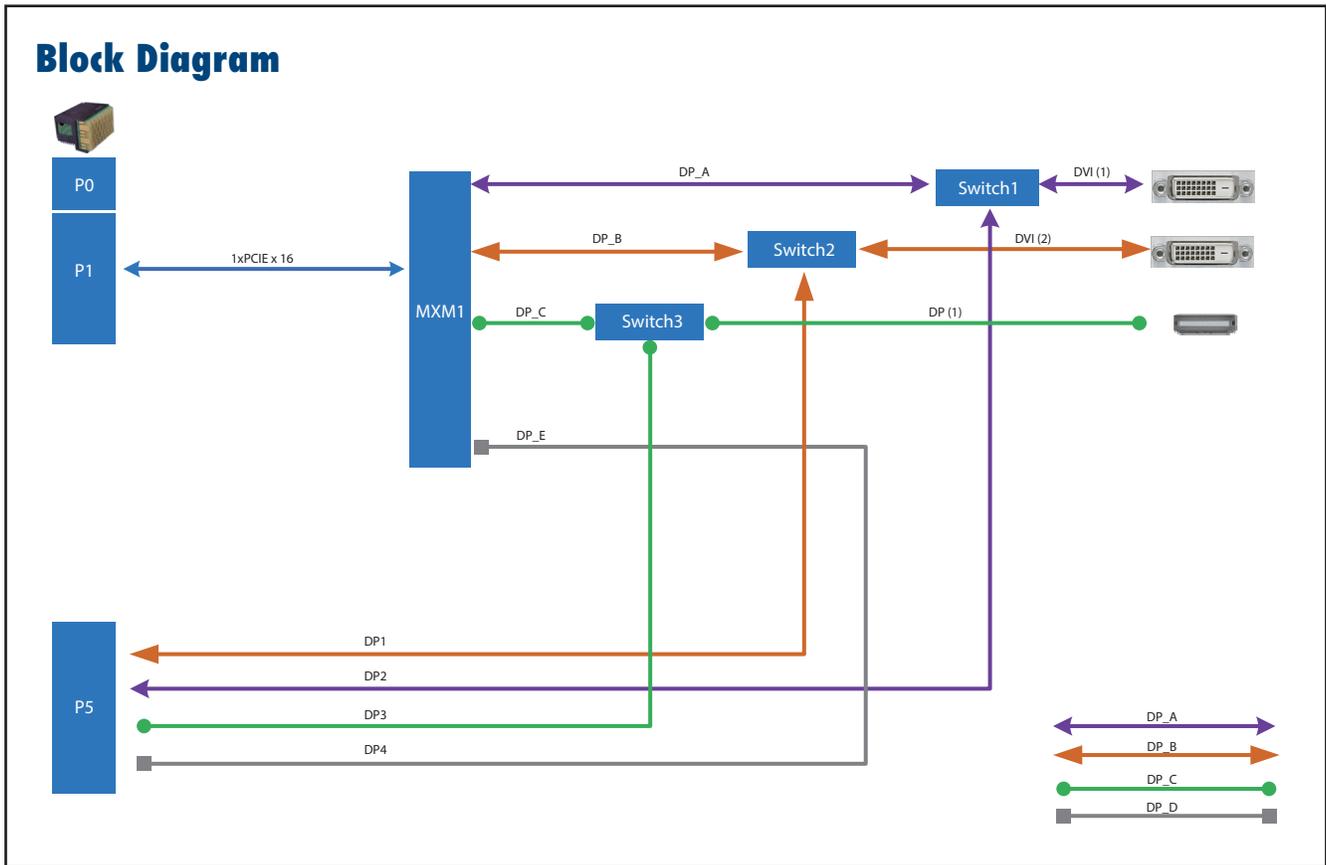
Offering up to four independent display outputs, MIC-6110 can auto-select the outputs between the backplane and the front panel I/O to fulfill the requirement of the multiple displays. With the selected MXM, MIC-6110 offers the great computing ability for assisting the main processor board computation.

With the native design for the maximum compatibility of mechanical structures, MIC-6110 can be adapted to all sorts of 6U OpenVPX chassis, and is reliable to bear the harsh operational conditions such as the extreme temperature, shock, and vibration.

Specifications

VPX Interface	P0	Power: 12V
	P1	1 x PCIe x16
	P5	4 x Displayport
MXM interface		MXM 3.1 Type A/ Type B
Power output	MXM	12V@10A
Front panel I/O ports (Available for air-cooled model only)		2 x DVI; 1 x Displayport (Output capability depends on the MXM selected)
Operating System	Compatibility	Windows 7 or above; Linux (Depends on the selected MXM module)
Power Requirement	SKU1	71 W total power envelope with GTX 1060 MXM module
Physical Characteristics	Dimensions	160.00 x 100.00 mm (6.3" x 3.95") (W x D), 5HP (H)
	Weight	0.8 kg without peripherals
Environment (POR)	Temperature	Operating: -30 – +85 °C Non-operating: -55 – +105 °C (Depends on the selected MXM module)
	Humidity	95%@40°C, non-condensing 95%@60°C, non-condensing
	Operation Shock	VITA 47, OS2
	Vibration	VITA 47, V3
	Altitude	50,00ft above sea level, 60,000ft, -40°C above sea level
Compliance	VPX	OpenVPX (VITA 65), REDI (VITA 48)

Block Diagram



Related Products

Product	Description
MIC-6314	OpenVPX CPU Blade with 4th/ 5th Generation Intel® Core™ Processor

Configuration

Part number	MXM module	GPU	Heatsink	Other mechanical parts
MIC-6110-C1APE	Aetina M3N1060-MN	NVidia GTX1060	Ruggedized convection cooled	Front panel; handles
MIC-6110-C1CPE	Aetina M3N1060-MN	NVidia GTX1060	Ruggedized convection cooled	Wedglock; handles
MIC-6110-B0NOE	None	None	None	None

Ordering Information

Model number	Configuration
MIC-6110-C1APE	MIC-6110 with Aetina M3N1060-MN
MIC-6110-C1CPE	MIC-6110 with Aetina M3N1060-MN for reinforced chassis
MIC-6110-B000E	MIC-6110 bare board

* Please contact the Advantech representative for the availability
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